

GBU10005~GBU1010

Rev.A.Aug.-2019

5 Ø / Descriptions

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 Glass Passivated Bridge Rectifiers, Reverse Voltage:50~1000V,Forward Current:10.0A,GBU package.

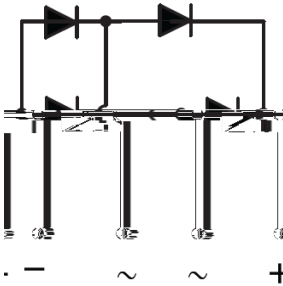
/ " / Features

i PCB Æ # + k.> % ÀÙÓk.> UL É ~ ^ . 94V-0o)í D }o
 Ideal for printed circuit board, Case material molded plastic, The plastic material has U/L flammability classification 94V-0. Halogen free product.

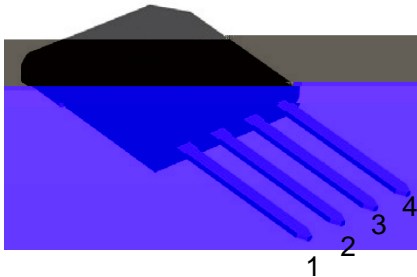
— ÷ / Applications

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 General purpose.

^ W] Ô• / Equivalent Circuit



Û- æ / Pinning



PIN1 y DC- PIN2 y AC PIN 3 y AC PIN 4 y DC+

Z ÜB , M V / h_{FE} Classifications & Marking

- ~ " Øo See Marking Instructions

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绝对最大额定值(Ta=25℃)

Parameter	Symbol	Rating							Unit
		GBU 10005	GBU 1001	GBU 1002	GBU 1004	GBU 1006	GBU 1008	GBU 1010	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current(with heatsink Note 2)	$I_{F(AV)}$	10.0							A
Maximum Average Forward Rectified Current @T _C =100 (without heatsink)		3.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load (JEDEC Method)	I_{FSM}	220							A
I ² t Rating for Fusing (t<8.3ms)	I ² t	200							A ² s
Typical Junction Capacitance Per Element (Note1)	C _J	86							pF
Typical Thermal Resistance (Note2)	R _{Jc}	2.0							/W
Operating Temperature Range	T _j	-55 to +150							
Storage Temperature Range	T _{stg}	-55 to +150							

NOTE:

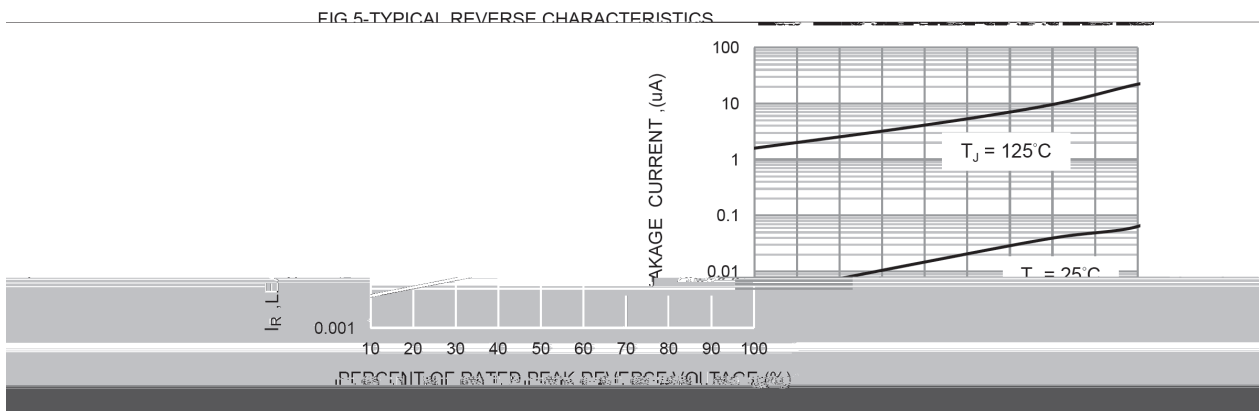
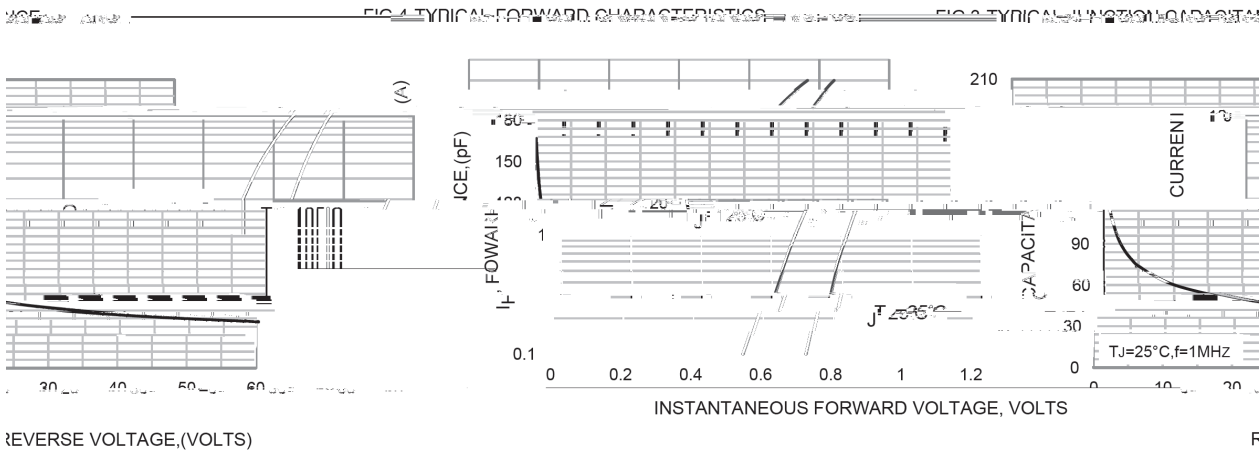
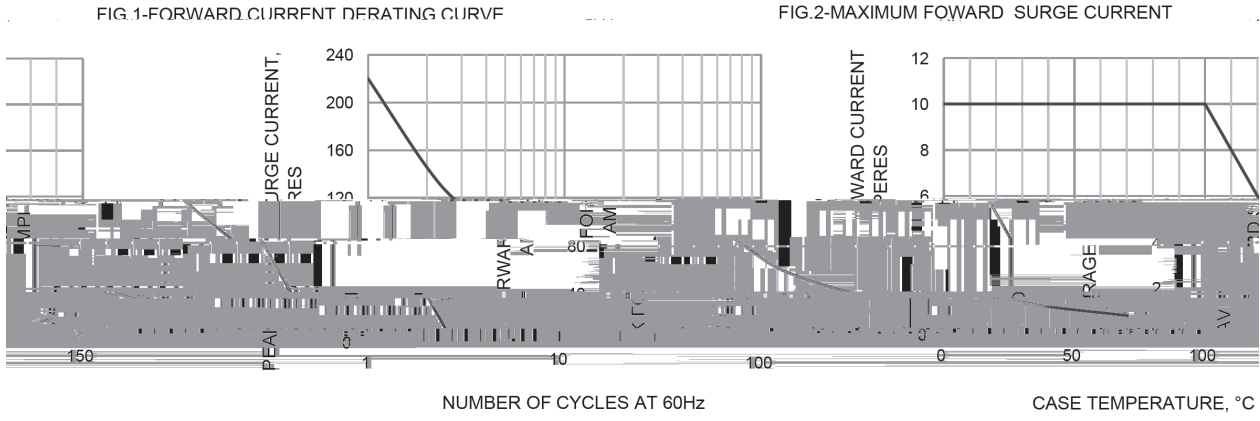
1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2.Device mounted on 150mm*150mm*1.6mm Cu Plate Heatsink.

电 气 特 性 (Ta=25℃)

Parameter	Symbol	Test Conditions	Rating	Unit
Maximum Forward Voltage	V_F	$I_F=5.0A$	1.0	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	T _a =25	5.0	A
		T _a =125	500	

Electrical Characteristic Curve

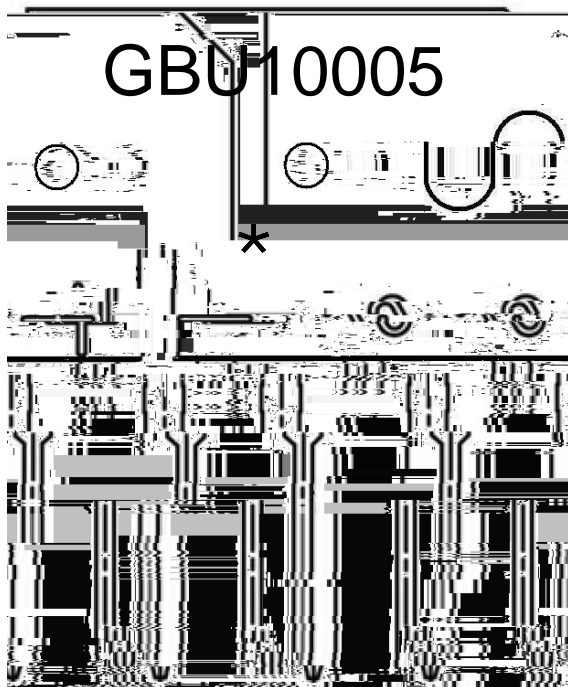


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DATA SHEET

, M y / Marking Instructions



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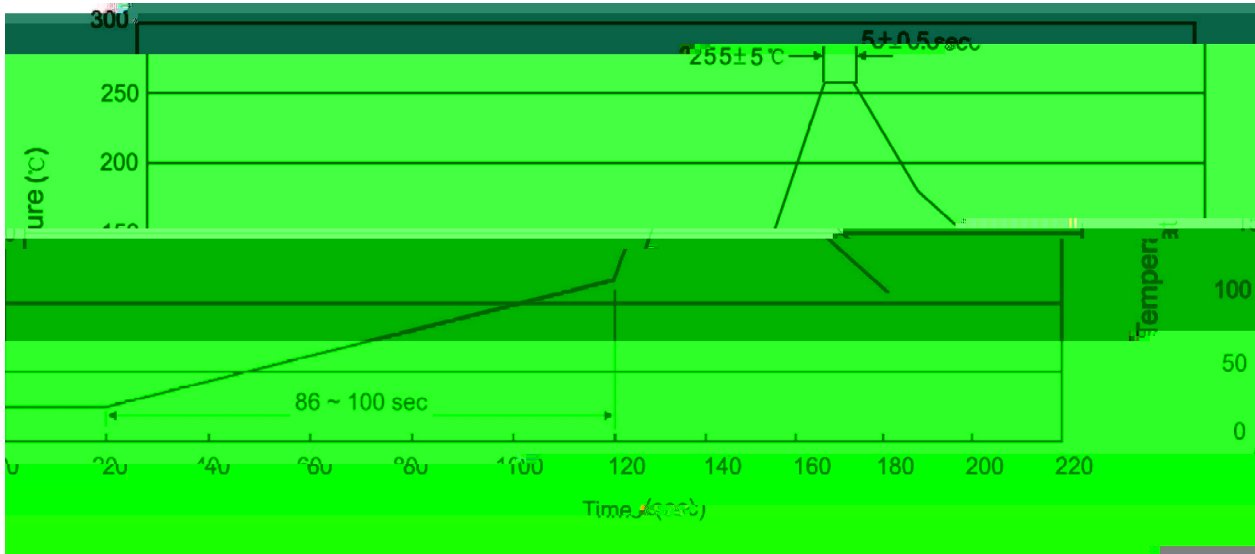
y ÿD Z W A k ÿD Z J

4 U Z K

GBU10005: Product Type.

****: Lot No. Code, code change with Lot No.

G PD t ϕ (x /) / Temperature Profile for Dip Soldering(Pb-Free)



- 1. Preheating: 25~150 °C, Time: 60~90sec;
- 2. Peak Temp.: 255 ± 5 °C, Duration: 5 ± 0.5sec;
- 3. Cooling Speed: 2~10 °C/sec.

- Note:
- 1. Preheating: 25~150 °C, Time: 60~90sec.
 - 2. Peak Temp.: 255 ± 5 °C, Duration: 5 ± 0.5sec.
 - 3. Cooling Speed: 2~10 °C/sec.

Resistance to Soldering Heat Test Conditions

Temperature: 270 ± 5 °C Time: 10 ± 1 sec Temp.: 270 ± 5 °C Time: 10 ± 1 sec

Package Type / Packaging SPEC.

Quantity: BULK

Package Type	Units (mm)					Dimension (mm) (unit: cm ³)		
	Length	Width	Height	Lead Length	Lead Spacing	Length	Width	Height
B	-	-	8	10	8	4	6	9

Notices